

IN THE CLAIMS:

Please amend the claims as shown below. The status of the claims after amendment will be as follows:

Claims 1 - 7 (cancelled)

8. (currently amended) A method of interconnecting terminals comprising:

placing terminals so as to oppose each other with an anisotropic electrically conductive resin composition including at least electrically conductive particles and a resin component which is not completely cured at the melting point of the electrically conductive particles disposed between the opposing terminals;

heating the resin composition to a temperature which is higher than the melting point of the electrically conductive particles and at which the resin component is not completely cured with the opposing terminals separated from each other by a space large enough to enable the particles to move laterally inside the space, wherein in the heating, the electrically conductive particles collect between the opposing terminals by melting and agglomeration of the electrically conductive particles, and the opposing terminals are electrically interconnected; and

curing the resin component.

9. (previously presented) A method of interconnecting

terminals as claimed in claim 8 wherein the resin component comprises a resin having reducing properties which can reduce at least one of the surface of the terminals and the surface of the electrically conductive particles.

10. (previously presented) A method of interconnecting terminals as claimed in claim 8 including completely filling the space between members on which the terminals are provided with the resin composition.

11. (currently amended) A method of mounting a semiconductor device comprising:

placing electrode pads of a semiconductor chip opposite circuit electrodes provided on a circuit substrate so as to correspond to the electrode pads with an anisotropic electrically conductive resin composition including at least electrically conductive particles and a resin component which is not completely cured at the melting point of the electrically conductive particles disposed between the opposing electrode pads and circuit electrodes;

heating the resin composition to a temperature which is higher than the melting point of the electrically conductive particles and at which the resin component is not completely cured with the opposing electrode pads and circuit electrodes separated from each other by a space large enough to enable the particles to move laterally inside the space, wherein in the heating, the electrically conductive particles collect between the opposing

electrode pads and circuit electrodes by melting and agglomeration of the electrically conductive particles, and the opposing electrode pads and circuit electrodes are electrically interconnected; and

curing the resin component.

12. (previously presented) A mounting method as claimed in claim 11 including completely filling the space between the semiconductor chip and the circuit substrate with the resin composition

13. (new) A mounting method as claimed in claim 12 wherein during the heating, substantially all of the electrically conductive particles in the resin composition collect in regions between opposing electrode pads and circuit electrodes.

14. (new) A mounting method as claimed in claim 11 including performing the heating with the opposing electrode pads and circuit electrodes separated from each other by a distance which is at least a multiple of the diameter of the particles.

15. (new) A method of interconnecting terminals as claimed in claim 8 including performing the heating with the terminals separated from each other by a distance which is at least a multiple of the diameter of the particles.